

AMENDMENTS TO THE CLAIMS:

Claims 1-97 (cancelled)

98. (Previously presented) A method for mounting an electronic component, comprising:
forming a ball at a tip of a metal wire;
forming said ball into a bump by thermocompression bonding said ball to a first electrode of an electronic component;
shaping a tip of said bump without collapsing said bump by applying a load of not greater than 20 gf to said bump; and then
with an insulating resin layer, including a mixture of an insulating resin and an inorganic filler, interposed between said electronic component and a circuit board while said first electrode is aligned with a second electrode of said circuit board,
(i) applying a first pressure to said electronic component while applying heat to said insulating resin, and then
(ii) while no longer applying said first pressure, applying a second pressure to said electronic component, with said second pressure being less than said first pressure,
thereby bonding said electronic component to said circuit board by hardening said insulating resin layer such that said first electrode becomes electrically connected to said second electrode via said bump.

99. (Previously presented) The method according to claim 98, wherein
said first pressure is not less than 20 gf per bump, and said second pressure is not greater than one half said first pressure.

Claims 100-142 (cancelled)